

3rd Generation Intel® Core™ Processor AdvancedMC™ Module



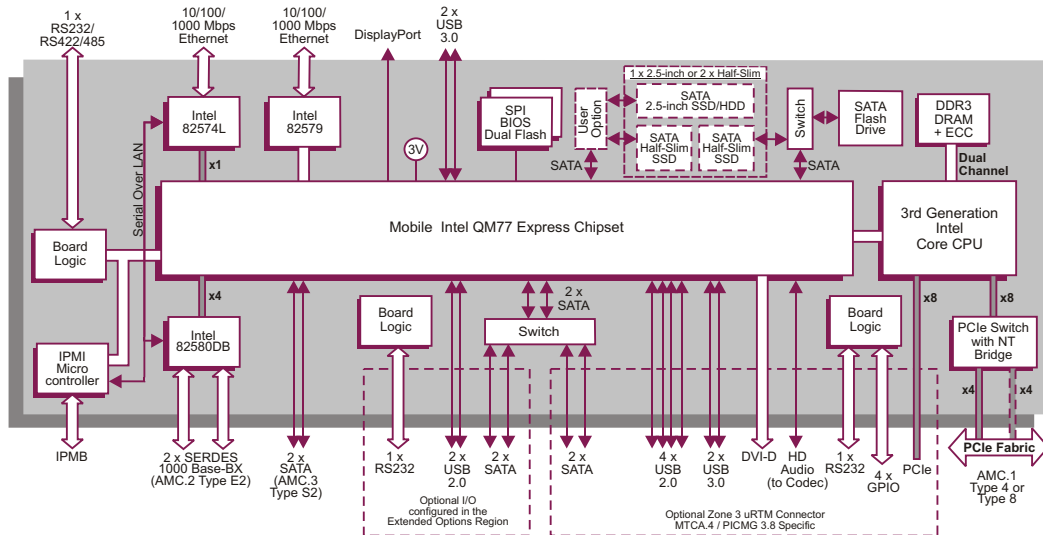
APPLICATIONS

AM 90x/x1x is a full or mid-size AdvancedMC™ processor module based on a 3rd generation Intel® Core™ i7/i5 processor giving an excellent balance of processing and graphics capability for long life-cycle deployments. This double module is available in conjunction with an optional rear transition module targeted to high speed physics applications, in addition to AdvancedTCA® and MicroTCA® deployments for

applications in the telecommunications, scientific, and industrial markets. AM 90x/x1x features an array of interfaces and has options for SATA based 2.5-inch, half-slim and a soldered solid-state Flash drive for high speed, reliable on-board storage. A range of industry standard operating systems are supported for easy integration.

HIGHLIGHTS

- Double Module, Full-size or Mid-size, AdvancedMC™ processor module:
 - compliant to AMC.0
- Build options available:
 - compliance with SCOPE Alliance
 - compatibility with MTCA.4 (MTCA for Physics), with or without a µRTM connector
 - I/O within the extended options region
- 3rd generation Intel® Core™ processor:
 - 4-core 2.1 GHz Intel Core i7-3612QE processor
 - 2-core 2.5 GHz Intel Core i7-3555LE processor
- Up to 16 Gbytes of DDR3-1600 ECC DRAM
- up to x8 PCI Express® (Gen 1, Gen 2 and Gen 3) fabric port:
 - dual x4 or single x8 Fat Pipes
 - AMC.1 Type 4 or AMC.1 Type 8
- 4 x Gigabit Ethernet interfaces:
 - AMC.2 Type E2 (2 interfaces, SerDes type)
 - 2 additional interfaces via front panel RJ45 connectors
- up to 4 x SATA interfaces on rear I/O:
 - 2 x SATA, AMC.3 Type S2
 - and 2 x SATA via extended options region or 2 x SATA via µRTM
- 2 x SATA interfaces for optional onboard storage:
 - 2.5-inch storage drive and soldered Flash drive
 - or 1 x half-slim SSD and soldered Flash drive
 - or up to 2 x half-slim SSDs
- USB port interfaces:
 - 2 x USB 3.0 ports via front panel
 - 2 x USB 2.0 via extended options region
 - 4 x USB 2.0 and 2 x USB 3.0 ports via µRTM
- Up to 3 serial port interfaces:
 - 1 via front panel
 - 1 via extended options region and 1 via µRTM
- DisplayPort graphics interface via front panel
- DVI-D graphics interface via µRTM
- Watchdog timer and Long Duration Timer
- 8 Mbytes of BIOS Flash EPROM, dual devices
- Hot swap compliant:
 - compliant to AMC.0
- IPMI (Intelligent Platform Management Interface):
 - IPMI Version 1.5 according to AMC.0 plus support for Serial Over LAN (SOL)
 - future support for IPMI Version 2.0
- Optional µRTM available (part number AD AM1/x01)
- Support for support for Linux®, Windows® and VxWorks®



Double Module AMC SBC

- build options available:
 - compliance with SCOPE Alliance
 - compatibility with MTCA.4 (MTCA for Physics), with or without a µRTM connector
 - I/O interfaces within Extended Options Region
- optional µRTM available:
 - see AD AM1/x01 datasheet

Central Processor

- 3rd generation Intel® Core™ processors:
 - 4-core 2.1 GHz Intel Core i7-3612QE processor
 - 2-core 2.5 GHz Intel Core i7-3555LE processor
 - up to 6 Mbytes of shared Last-Level on-die cache
- utilizes Mobile Intel® QM77 Express Chipset

DRAM

- up to 16 Gbytes DDR3-1600 ECC DRAM:
 - soldered
 - single bit error correction
 - peak bandwidth of 25 Gbytes/s
 - dual channel architecture
- accessible from processor and AMC connector

PICMG AdvancedMC™ Interfaces

- hot swap compliant to AMC.0
- single x8 or dual x4 PCI Express® fabric connection:
 - AMC.1 Type 4 or Type 8
 - support for Gen 1, Gen 2 or Gen 3
 - transfer rate up to 8 Gbytes/s
 - supported by a DMA engine in the PCI Express switch
 - can be used as two x4 interfaces in dual redundant fabric systems
 - external or on-board fabric clock support
- x8 PCI Express from processor via µRTM
- rear I/O compliant to AMC.1 specification

Storage Interfaces

- up to 4 x SATA300 interfaces on rear I/O:
 - 2 x SATA, AMC.3 Type S2
 - and optionally 2 x SATA interfaces via extended options region or 2 x SATA via µRTM
- 2 x SATA600 interfaces for optional onboard storage:
 - 2.5-inch HDD/SSD and soldered Flash Drive
 - or 1 x half-slim SSD and soldered Flash Drive
 - or up to 2 x half-slim SSDs

Ethernet Interfaces

- dual SerDes interfaces via AMC connector:
 - AMC.2 Type E2
 - supporting 1000Base-BX
 - implemented by Intel® 82850DB LAN Controller via x4 PCI Express port
- 2 x front panel 10/100/1000 Mbps interface accessed via RJ45 connectors, implemented by:
 - Intel® 82579LM Gigabit Ethernet PHY
 - Intel® 82574L Gigabit Ethernet controller

Serial Interfaces

- serial port interfaces:
 - 1 x RS232/422/485 port via DB9 front panel connector
 - optionally 1 x RS232 port via extended options region (TXD, RXD, RTS and CTS)
 - or optionally 1 x RS232 port via µRTM
- 16550 compatible UARTs
- modem control signals supported:
 - front: TxD, RxD, CTS, RTS, DCD, DTR, DSR, RI
 - µRTM rear: TxD, RxD, CTS, RTS, DCD, DTR, DSR

Display Interfaces

- implemented by the integrated chipset graphics controller and dual independent display
- DisplayPort connector on front panel:
 - up to 2560x1600, 32-bit, 60Hz
- digital DVI-D via µRTM:
 - up to 1600 x 1200
 - up to 32-bit color depth
- support for Microsoft® DirectX 10
- support for OpenGL 2.0, Windows and Linux

Other Peripheral Interfaces

- PC-compatible Real Time Clock
- watchdog timer
- 1 x 32-bit Long Duration Timer with processor interrupt capability
- CPU temperature monitor; voltages monitor:
 - all accessible via IPMI
- 4 x GPIO signals via µRTM
- USB port interfaces:
 - 2 x USB 3.0 ports via front panel
 - optionally 2 x USB 2.0 ports via extended option region
 - or optionally 2 x USB 3.0 ports via µRTM and 4 x USB 2.0 ports via µRTM

Software Support

- support for support for Linux®, Windows® and VxWorks®

Firmware Support

- Insyde Software InsydeH20™ BIOS:
 - includes Compatibility Support Module
- based upon Intel® Platform Innovation Framework for EFI
- comprehensive Power-On Self-Test (POST)
- LAN boot firmware included

Flash EPROM

- 8 Mbytes of BIOS Flash EPROM, dual devices:
 - main/backup device enabled via switch

IPMI

- IPMI Version 1.5 according to AMC.0 plus support for Serial Over LAN (SOL)
- future support for IPMI Version 2.0
- on-board BMC (Baseboard Management Controller)
- supports 8 Kbytes of non-volatile memory

Electrical Specification

- +12V @ 3.8A (typical current figure with 2.1 GHz Intel Core i7-3612QE processor, 8 Gbytes DRAM), voltage ±2V
- +3.3V @ 0.13A maximum, voltage ±5%

Safety

- PCB (PWB) manufactured with flammability rating of UL94V-0

Environmental Specification

- operating temperature:
 - 0°C to +55°C (N-Series)
- non-operating temperature: -40°C to +85°C
- 5% to 95% Relative Humidity, non condensing (operating or non-operating)

Mechanical Specification

- AMC.0 Double Module form-factor:
 - 181mm x 149mm (7.1 inches x 5.8 inches)
- Full-size panel: 29mm (1.1 inches):
 - Mid-size version available

ORDERING INFORMATION

Order Number Product Description (Hardware)

AM 90x/21x-yz 3rd generation Intel Core processor, Double Module, Full-size AMC
 AM 90x/41x-yz 3rd generation Intel Core processor, Double Module, Mid-size AMC

For the order number suffix (yz) options please contact your local sales office:

Where y = rear I/O options
 y - rear I/O build options

Where z = DRAM size
 z - up to 16 Gbytes

For accessories please contact your local sales office.

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